



#7/Amend B
A700
5/25/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 6131
Norihiro TSUKAHARA et al. : Docket No. 2002_0024A
Serial No. 10/031,000 : Group Art Unit 2825
Filed January 16, 2002 : Examiner C. Everhart

SEMICONDUCTOR DEVICE PACKAGE
MANUFACTURING METHOD AND
SEMICONDUCTOR DEVICE PACKAGE
MANUFACTURED BY THE METHOD

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of December 20, 2002, the period for response having been extended for two (2) month by the attached petition, please amend the present application as follows:

In the Specification:

Please delete the paragraph before the title of the invention at page 1.

Please insert the heading beginning at page 1, line 4, with the following heading:

BACKGROUND OF THE INVENTION

05/21/2003 CCHAU1 00000104 10031000

02 FC:1202 180.00 OP
03 FC:1201 168.00 OP

Adjustment date: 05/27/2003 AF0001

05/21/2003 CCHAU1 00000104 10031000

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Please replace the heading beginning at page 1, line 23, with the following heading:

B2 2. Description of the Related Art

Please replace the heading beginning at page 4, line 23, with the following heading:

B3 SUMMARY OF THE INVENTION

Please replace the heading beginning at page 20, line 16, with the following heading:

B4 BRIEF DESCRIPTION OF THE DRAWINGS

Please replace the heading beginning at page 26, line 19, with the following heading:

B5 DETAILED DESCRIPTION OF THE INVENTION

Please replace the paragraph beginning at page 29, line 16, with the following rewritten paragraph:

B4
Next, in step S4, as shown in Fig. 3D, by placing the thermoplastic resin sheet 7a on a hot pressing plate 8B arranged opposite to a hot pressing plate 8A, holding the thermoplastic resin sheet 7a on which the semiconductor device 3 is mounted between the hot pressing plates 8A and 8B, and pressurizing the hot pressing plate 8A against the hot pressing plate 8B relative to each other, hot pressing is carried out to melt the